

**Apparatus and method for lapping magnetic heads**

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**Abstract**

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An apparatus for lapping a workpiece including a plurality of magnetic heads supported by a tool is disclosed. The lapping apparatus comprises a rotary lapping table, a lapping head attachment frame, an adjuster ring resiliently supported by the frame, a lapping head attached to the adjuster ring, a tilting assembly attached to the lapping head, and an up and down movable back plate pivotally attached to the lapping head. The apparatus further comprises first actuators or cylinders for correcting balance by applying forces on right and left sides of the pivotal point of the back plate, and second actuators or cylinders for correcting bow of the workpiece by applying operating forces on a plurality of predetermined locations of the tool so that the moving directions of movable parts of the second actuator means are substantially parallel with the directions of the operating forces

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